

INTERCONNECTING SUBSTRATES FOR MICROELECTRONIC DIES,
METHODS FOR FORMING VIAS IN SUCH SUBSTRATES, AND
METHODS FOR PACKAGING MICROELECTRONIC DEVICES

ABSTRACT OF THE DISCLOSURE

Substrates for mounting microelectronic dies, methods for forming vias in such substrates, and methods for packaging microelectronic devices are disclosed herein. A method of manufacturing a substrate in accordance with one embodiment of the invention includes forming a conductive trace on a first side of a sheet of non-conductive material, and forming a via through the non-conductive material from a second side of the sheet to the conductive trace. The method further includes removing a section of the non-conductive material to form an edge of the non-conductive material extending across at least a portion of the via. In one embodiment, forming the edge across the via exposes at least a portion of the second conductive trace for subsequent attachment to a terminal on a microelectronic die.

Figure : 3A